

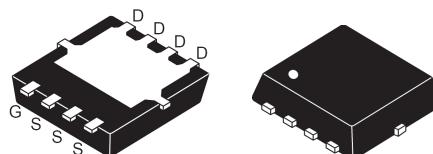
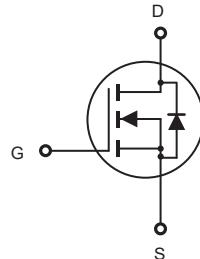


# CEZC16R10LA

## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 100V, 29A,  $R_{DS(ON)} = 16\text{m}\Omega$  @ $V_{GS} = 10\text{V}$ .  
 $R_{DS(ON)} = 24\text{m}\Omega$  @ $V_{GS} = 4.5\text{V}$ .
- Super High dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- RoHS compliant.



P-PAK 3X3

### ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D @ R_{JC}$	29	A
	$I_D @ R_{JA}$	9	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM} @ R_{JC}$	116	A
	$I_{DM} @ R_{JA}$	36	A
Maximum Power Dissipation	$P_D$	25	W
Single Pulsed Avalanche Energy <sup>e</sup>	$E_{AS}$	10	mJ
Single Pulsed Avalanche Current <sup>e</sup>	$I_{AS}$	4.5	A
Operating and Store Temperature Range	$T_J, T_{Stg}$	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case <sup>b</sup>	$R_{JC}$	5	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{JA}$	50	$^\circ\text{C/W}$



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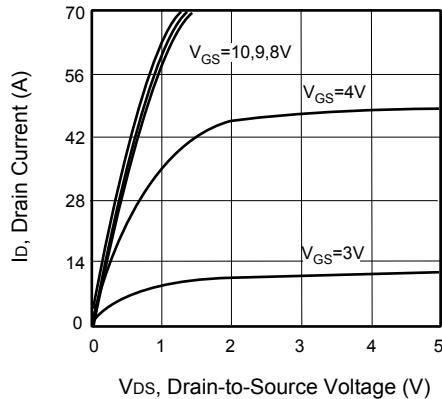
## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$		10		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics<sup>c</sup></b>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	1		2.5	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 12\text{A}$		13.4	16	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 7\text{A}$		18.4	24	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>d</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		900		pF
Output Capacitance	$C_{\text{oss}}$			205		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			15		pF
<b>Switching Characteristics<sup>d</sup></b>						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 50\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		17		ns
Turn-On Rise Time	$t_r$			4		ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			42		ns
Turn-Off Fall Time	$t_f$			20		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 50\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 4.5\text{V}$		11.5		nC
Gate-Source Charge	$Q_{\text{gs}}$			1.7		nC
Gate-Drain Charge	$Q_{\text{gd}}$			7.8		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				20	A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 12\text{A}$			1.2	V

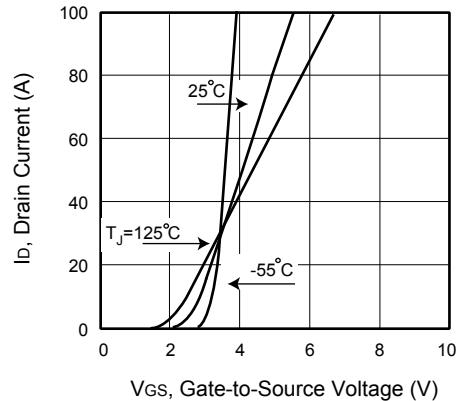
Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Surface Mounted on FR4 Board,  $t \leq 10$  sec.
- c.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $< 2\%$ .
- d.Guaranteed by design, not subject to production testing.

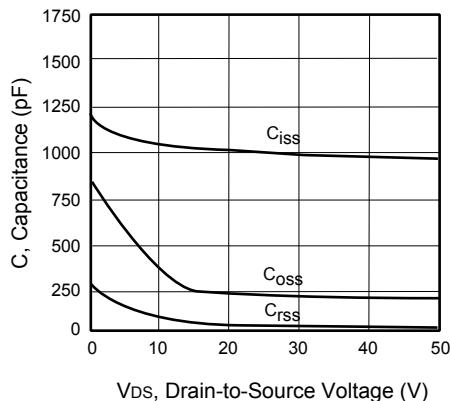
e.L = 1mH,  $I_{AS} = 4.5\text{A}$ ,  $V_{DD} = 24\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$ .



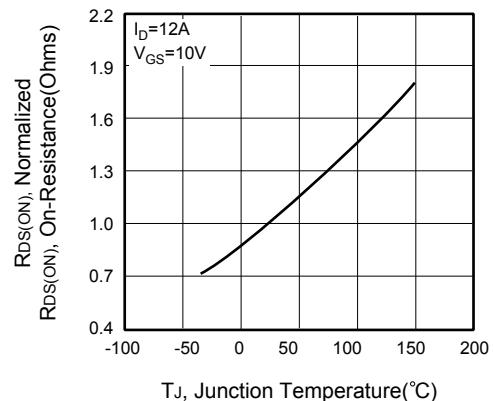
**Figure 1. Output Characteristics**



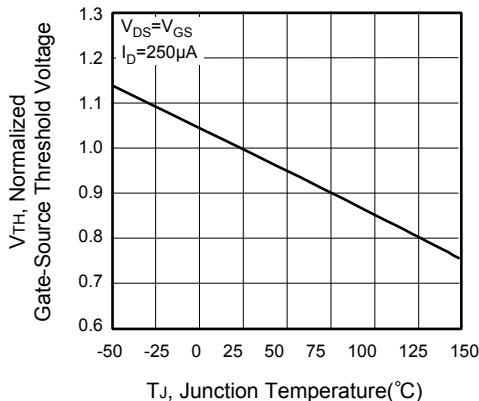
**Figure 2. Transfer Characteristics**



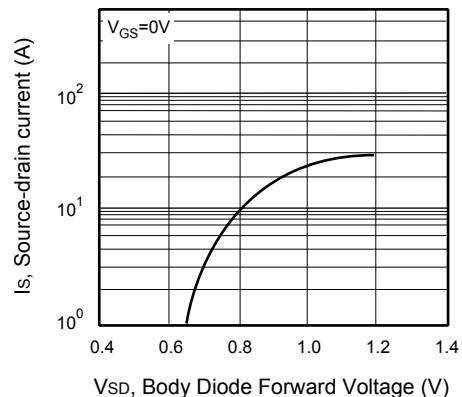
**Figure 3. Capacitance**



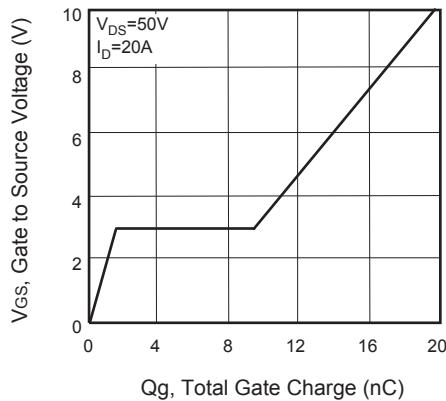
**Figure 4. On-Resistance Variation with Temperature**



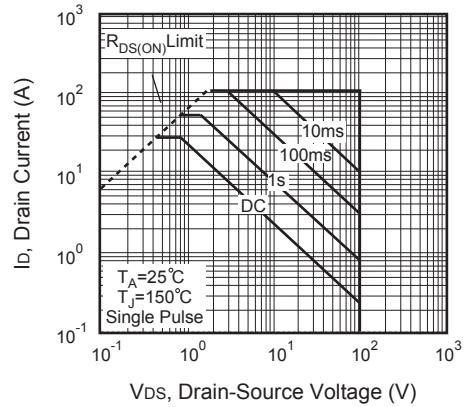
**Figure 5. Gate Threshold Variation with Temperature**



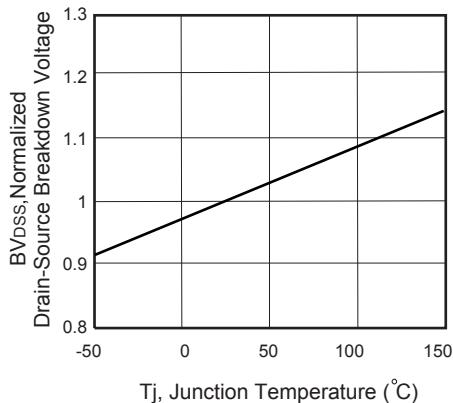
**Figure 6. Body Diode Forward Voltage Variation with Source Current**



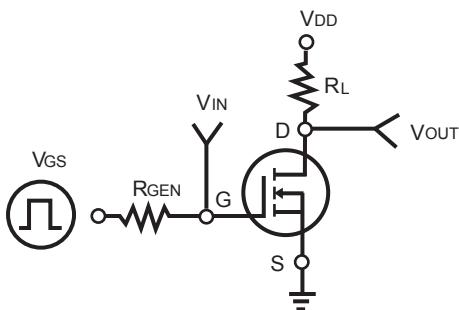
**Figure 7. Gate Charge**



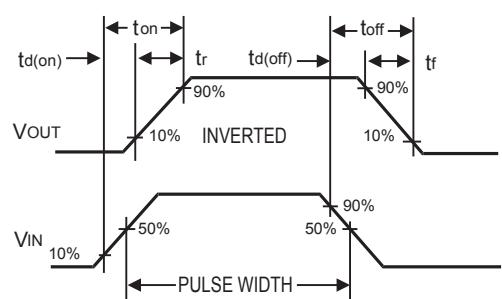
**Figure 8. Maximum Safe Operating Area**



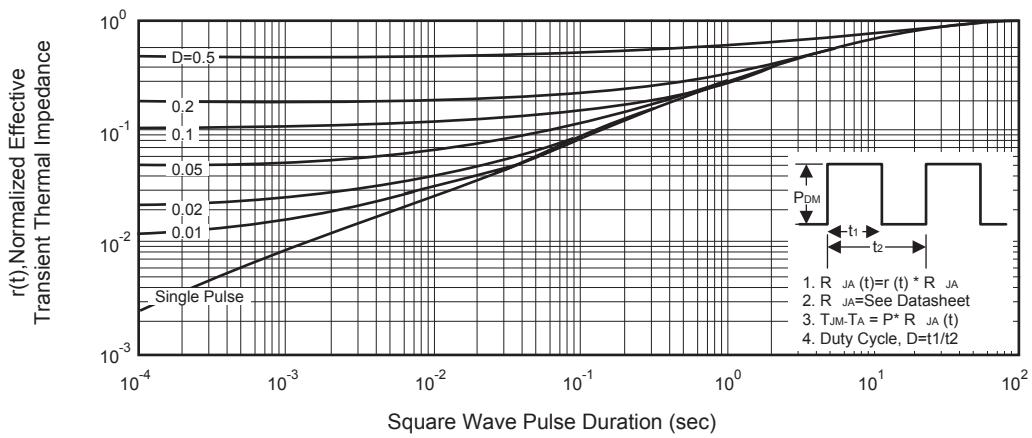
**Figure 9. Breakdown Voltage Variation VS Temperature**



**Figure 10. Switching Test Circuit**



**Figure 11. Switching Waveforms**



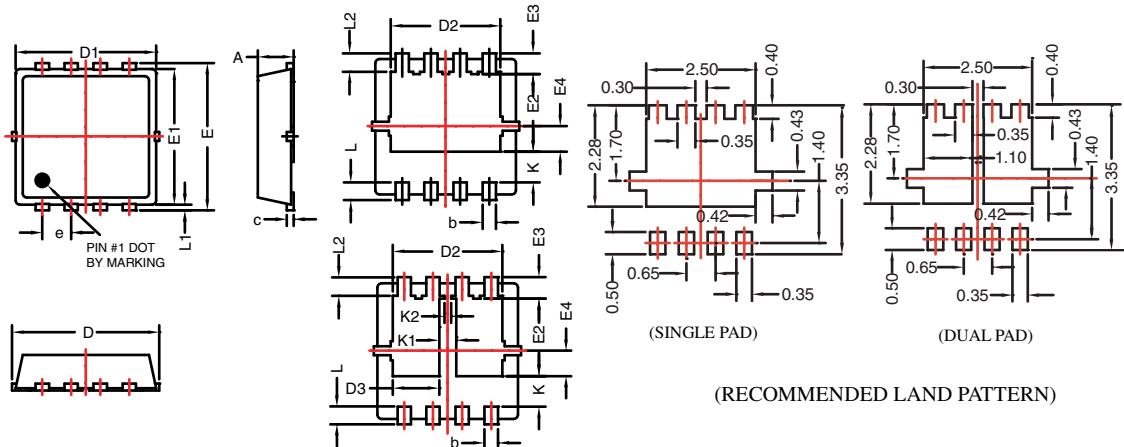
**Figure 12. Normalized Thermal Transient Impedance Curve**



# CEZC16R10LA

P-PAK3X3

(Product Outline Dimension)



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.7	0.85	0.028	0.033
b	0.20	0.40	0.008	0.016
c	0.10	0.25	0.004	0.010
D	3.15	3.45	0.124	0.136
D1	3.00	3.25	0.118	0.128
D2	2.29	2.65	0.090	0.104
D3	0.84	1.24	0.033	0.049
E	3.15	3.45	0.124	0.136
E1	2.90	3.20	0.114	0.126
E2	1.54	1.94	0.061	0.076
E3	0.28	0.65	0.011	0.026
E4	0.37	0.77	0.015	0.030
e	0.65(BSC)		0.026(BSC)	
K	0.50	0.89	0.02	0.035
K1	0.30	0.53	0.019	0.021
K2	0.15	0.35	0.006	0.014
L	0.30	0.50	0.012	0.020
L1	0.06	0.20	0.002	0.008
L2	0.27	0.57	0.011	0.022